

MEG01-004

Serial number 09/837,007

REMARKS

Examiner James M. Mitchell is thanked for thoroughly reviewing the instant application and for examining the Prior Art.

Favorable reconsideration of this application in light of the above amendments and the following remarks is respectfully requested.

A new method and package is provided for the mounting of semiconductor devices that have been provided with small-pitch Input/Output interconnect bumps. Fine pitch solder bumps, consisting of pillar metal and a solder bump, are applied directly to the I/O pads of the semiconductor device, the device is then flip-chip bonded to a substrate. Dummy bumps may be provided for cases where the I/O pads of the device are arranged such that additional mechanical support for the device is required.